



FLIP CHIP MODULES TEST SPECS

TYPE: MI 69

GATING MODULE

TEST	CONDITIONS	MINIMUM	MAXIMUM
V_{OUT} (0)	$V_{CC} = +4.75V$ $V_{IN} = +0.8V$ $I_{SINK} = +16 MA$	/	+0.4 V
V_{OUT} (1)	$V_{CC} = +4.75V$ $V_{IN} = +2.0V$ $I_{SINK} = -400 \mu A$	+ 2.4 V	/
I_{IN} (0)	$V_{CC} = +5.25V$ $V_{IN} = +0.4 V$	/	- 1.6 MA
i_{IN} (1)	$V_{CC} = +5.25V$ $V_{IN} = +2.4 V$	/	+ 40 μA
TD_1	$V_{CC} = +5.0 V$ + 1.5V TO + 1.5V *	/	45 NSEC
TD_0	$V_{CC} = +5.0 V$ + 1.5V TO + 1.5V *	/	45 NSEC

* RC LOAD - C = 150 PF TO GND, R = 330 Ω TO +4.75V

TECHNICAL INFORMATION

Instruction literature and technical bulletins are available on all digital products, if you would like to be added to our mailing list for this type of material or if you have any questions about the equipment you have purchased, please contact the nearest Digital Sales Office.

MAINTENANCE INFORMATION

8/28/68

Repair of printed circuitry should be done with a low voltage, fairly cool soldering iron to prevent damage to the transistors and keep the copper from lifting. Oscilloscopes used to troubleshoot a module or system should be grounded to prevent damaging transients.